

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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TGPK27B

T-Stick Blue - Phase Change Thermal Stick

Version 2.130218

T-Stick Blue - Phase Change Thermal Stick (also available in pink, see TGPK27P)

TGPK27B is a light blue coloured, thermally conductive phase change (PCM) material. It is a solid at room temperature but changes phase at 55°C which allows it to wet surfaces. TGPK27B is supplied in an easy to use format so that it can be manually applied to a wide range of surfaces. The unique formulation gives an exceptionally low thermal resistance for heat transfer in the most demanding of applications.

Features

Designed to maximize heat sink performance and improve component reliability Displaces entrapped air between power-dissipating electronic components Bond Line Thickness (BLT) of 0.0254mm

Practically no thermal contact resistance due to a very small thermal resistance path Solid at room temperature for ease of application

Consistently and cleanly applied as dry pads to a heat sink or component surface Resistant to dry out and pump out

Applications

Dissipation of heat in electronic devices is a critical and ever growing need as circuit board power densities continue to rise. To address this need, this product can be easily and cleanly applied in a wide variety of electronics thermal interface material requirements where the heatsink is being attached with hardware. With a very thin bondline of down to 0.0254mm, it is able to reduce the overall thermal resistance from the component to the heatsink. This keeps the components cooler which allows the electrical device to perform better. TGPK27B is not be used as an electrically insulative product.

Properties

- ✓ REACH Compliant
- ✓ ROHS Compliant

Property	TGPK27B	Unit	Tolerance	Test Method
Binder	Paraffin wax	-	-	-
Colour	Light blue	-	-	Visual
Specific Gravity	1.4	-	-	ASTM D792
Thermal Conductivity	1.0	W/mK	-	ASTM D5470
Melting point	52	°C	-	ASTM D127
Operating temperature	-40 to 200	°C	-	-
Shelf life	5	years	-	-

Part Number Information

Product	Colour	Packaging	Weight
TGPK27B	Light blue	Tube	27g

Product	Colour	Packaging	Weight
TGPK27P	Light pink	Tube	27g

^{*} All measurements in g

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^{*} Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.